

THERMALLY CONDUCTIVE MULTILAYERABLE EPOXY LAMINATE AND PREPREG



Arlon 92ML ceramic filled thermally conductive multifunctional epoxy laminate and prepreg products are provide best-in-class thermal performance with increased thermal conductivity of 2 W/mK for multilayer PWB's for applications requiring thermal management throughout the entire board volume.

Features:

- Thermal Conductivity 2.0 W/m-K, 6-8x that of FR-4, reduces hot-spots and dependence on thermal vias and heat-sinks to dissipate heat
- Glass Transition Temperature 170°C provides excellent plated through hole reliability, lead-free solder application
- Decomposition temperature >350°C is ideally suited for lead-free solder processing and offers significant improvement over other thermally conductive laminate materials
- Coefficient of Thermal Expansion close to that of Copper and Aluminum for planar stability during process
- Best-in-class thermal performance with T260>60 minutes, T280>15 minutes and T300 > 5 minutes.
- Electrical Strength >1000 Volts/mil for use in high power handling Applications
- Engineered for use with metal backing for producing Metal-Clad PCBs
- Meets the flammability requirements of UL-94 V-0
- Halogen-free per IPC4101 specifications

Typical Applications:

- High Brightness LED's
- DC-DC Power Converters
- Automotive Electronics
- Electronic designs with limited thermal management alternatives

Property	Units	Value	Test Method
1. Electrical Properties			
Dielectric Constant (will vary with Resin %)			
@ 1 MHz	-	5.2	IPC TM-650 2.5.5.3
@ 1 GHz	-	4.9	IPC TM-650 2.5.5.9
Dissipation Factor			
@ 1 MHz	-	0.013	IPC TM-650 2.5.5.3
@ 1 GHz	-		IPC TM-650 2.5.5.9
Volume Resistivity			
C96/35/90	MΩ-cm	1.7 x 10 ⁸	IPC TM-650 2.5.17.1
E24/125	MΩ-cm	2.9 x 10 ⁷	IPC TM-650 2.5.17.1
Surface Resistivity			
C96/35/90	MΩ	6.8 x 10 ⁷	IPC TM-650 2.5.17.1
E24/125	MΩ	2.7 x 10 ⁷	IPC TM-650 2.5.17.1
Electrical Strength	Volts/mil (kV/mm)	>1500	IPC TM-650 2.5.6.2
Dielectric Breakdown	kV	>50	IPC TM-650 2.5.6
Arc Resistance	sec		IPC TM-650 2.5.1
2. Thermal Properties			
Glass Transition Temperature (Tg)			
TMA	°C	180	IPC TM-650 2.4.24
DSC	°C	170	IPC TM-650 2.4.25
Decomposition Temperature (Td)			
Initial	°C	340	IPC TM-650 2.3.41
5%	°C	400	IPC TM-650 2.3.41
T260	min	>60	IPC TM-650 2.4.24.1
T288	min	>15	IPC TM-650 2.4.24.1
T300	min	>5	IPC TM-650 2.4.24.1
CTE (x,y)	ppm/°C	19-20	IPC TM-650 2.4.41
CTE (z)			
< Tg	ppm/°C	22	IPC TM-650 2.4.24
> Tg	ppm/°C	175	IPC TM-650 2.4.24
z-axis Expansion (50-260°C)	%	1.8	IPC TM-650 2.4.24
3. Mechanical Properties			
Peel Strength to Copper (1 oz/35 micron)			
After Thermal Stress	lb/in (N/mm)	5.0	IPC TM-650 2.4.8
At Elevated Temperatures	lb/in (N/mm)		IPC TM-650 2.4.8.2
After Process Solutions	lb/in (N/mm)	4.8	IPC TM-650 2.4.8
Young's Modulus	Mpsi (GPa)		IPC TM-650 2.4.18.3
Flexural Strength	kpsi (MPa)		IPC TM-650 2.4.4
Tensile Strength	kpsi (MPa)		IPC TM-650 2.4.18.3
Compressive Modulus	kpsi (MPa)		ASTM D-695
Poisson's Ratio (x, y)	-		ASTM D-3039
4. Physical Properties			
Water Absorption	%	0.12	IPC TM-650 2.6.2.1
Specific Gravity	g/cm ³	2.2	ASTM D792 Method A
Thermal Conductivity—Z-Axis	W/mK	2.0	ASTM E1461
Thermal Conductivity—X/Y-Axis	W/mK	3.5	ASTM E1461
Flammability	class	Meets V-0	UL-94

Results listed above are typical properties, provided without warranty, expressed or implied, and without liability. Properties may vary, depending on design and application. Arlon reserves the right to change or update these values. * Expected value based on similar systems

PRELIMINARY DATASHEET

Availability:

Arlon Part Number	Glass Style	Resin %	Nominal Press Thickness	Notes/Applications
92ML0488	104	88%	3.2	Multilayer
92ML0690	106	90%	4.2	Multilayer

Laminate available in a wide variety of thicknesses with 1/2, 1 or 2 oz copper. Inquire about Aluminum, Copper or Brass plate availability.

Recommended Process Conditions:

Process inner-layers through develop, etch, and strip using standard industry practices. Bake inner layers in a rack for 30 minutes at 225°F - 250°F (107°C - 121°C) immediately prior to lay-up. Vacuum desiccate the prepreg for 8 - 12 hours prior to lamination.

Lamination Cycle:

1) Control the heat rise to 9°F - 12°F (5°C - 7°C) per minute between 180°F and 280°F (82°C and 121°C)

2) Starting point laminating pressure for 92ML for standard panel sizes are as follows:

Panel Size		Pressure	
in	cm	psi	kg/sq cm
12 x 18	30 x 40	250-300	17-21
18 x 24	40 x 61	300-350	21-24

3) Product temperature at start of cure = 360°F (182°C).

4) Cure time at temperature = 90 minutes

5) Cool down under pressure at $\leq 10^\circ\text{F}/\text{min}$ ($5^\circ\text{C}/\text{min}$)

Drill at 350 SFM. Undercut bits are recommended for vias 0.018" and smaller

De-smear using alkaline permanganate or plasma with settings appropriate for multifunctional epoxy.

Conventional plating processes are compatible with 92ML

Standard profiling parameters may be used.

Bake for 2 hours at 250°F (121°C) prior to solder reflow

92ML

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